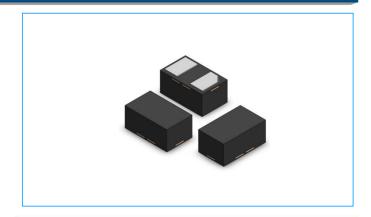


ESD2.5V88D-C

Description

The ESD2.5V88D-C is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium.



Feature

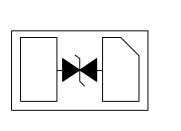
- ♦ 100 Watts Peak Pulse Power per Line (tp=8/20µs)
- ◆ Protects one Bidirectional I/O line
- ♦ Low clamping voltage
- Working voltages : 2.5V
- Low leakage current
- IEC61000-4-4 (EFT) 40A (5/50ηs)
- ◆ IEC61000-4-2(ESD):±30kV (air discharge)

±30kV (contact discharge)

Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Peripherals
- Pagers

Functional Diagram



Mechanical Data

- SOD-882/DFN1006 (1.0x0.6x0.5mm) Package
- ◆ Molding Compound Flammability Rating : UL 94V-O
- Weight 0.5 Milligrams (Approximate)
- ◆ Lead Finish : Lead Free

Mechanical Characteristics

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (tp=8/20µs waveform)	100	Watts
TL	Lead Soldering Temperature	260 (10 sec.)	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C
TJ	Operating Junction Temperature Range	-40 to +125	°C

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ESD2.5V88D-C

Electrical Characteristics (@ 25°C Unless Otherwise Specified)

Characteristics	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Reverse Working Voltage	V _{RWM}				2.5	V
Reverse Breakdown Voltage	V_{BR}	I _T =1mA;	2.85	-		V
Reverse Leakage Current	I _R	V _{RWM} =2.5V, T=25°C;			0.1	μΑ
Positive Clamping	V	I _{PP} =1A, T _P =8/20μs;			4.8	V
Voltage	Vc	I _{PP} =8A, T _P =8/20μs;			13	V
Junction capacitance	СJ	V _R = 0V, f = 1MHz;		15		pF

Characteristic Curves

Fig1. 8/20µs Pulse Waveform

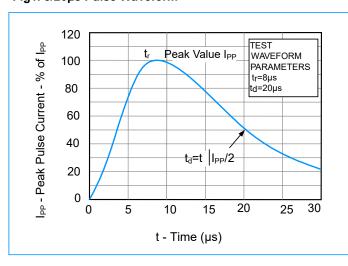


Fig2. Power Derating Curve

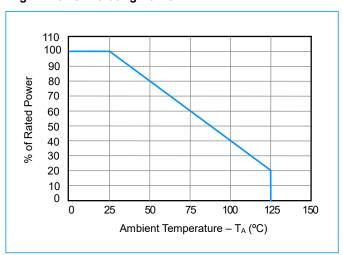


Fig3. ESD Pulse Waveform (according to IEC 61000-4-2)

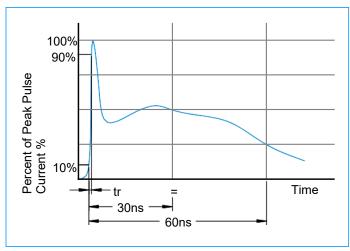
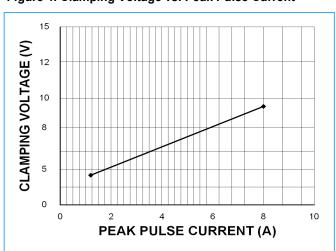


Figure 4. Clamping Voltage vs. Peak Pulse Current



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ESD2.5V88D-C

Characteristic Curves

Figure 5. Typic Breakdown Voltage vs. Temperature

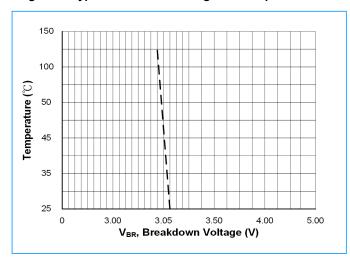
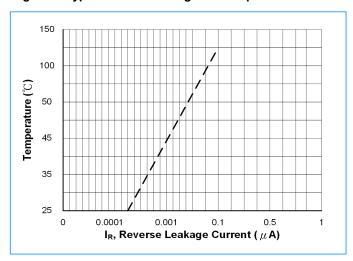
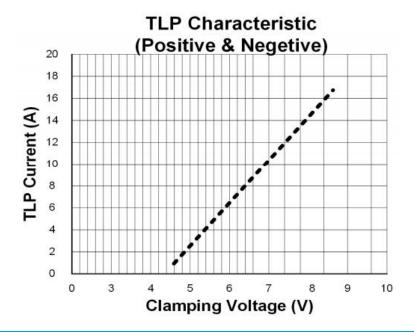


Figure 6. Typic Reverse Leakage vs. Temperature



Transmission Line Pulse (TLP)

Transmission Line Pulse (TLP) is a measurement technique used in the Electrostatic Discharge (ESD) arena to characterize performance attributes of devices under ESD stresses. TLP is able to obtain current versus voltage (I–V) curves in which each data point is obtained with a 100ns long pulse, with currents up to 40 A. TLP was first used in the ESD field to study human body model (HBM) in integrated circuits, but it is an equally valid tool in the field of system level ESD. The applicability of TLP to system level ESD is illustrated in Figure 1, which compares an 8KV IEC 61000–4–2 current waveform with TLP current pulses of 8 and 16 A. The current levels and time duration for the pulses are similar and the initial rise time for the TLP pulse is comparable to the rise time of the IEC 61000–4–2's initial current spike. This application note will give a basic introduction to TLP measurements and explain the data sheet parameters extracted from TLP for SDI Technology's protection products.

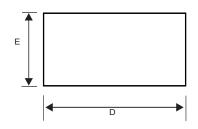


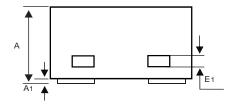


ESD2.5V88D-C

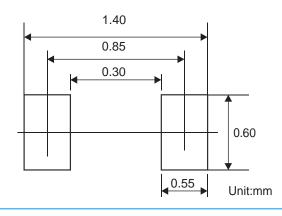
SOD-882/DFN1006 Package Outline & Dimensions

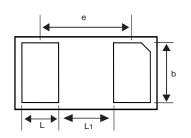
SOD-882/DFN1006





Suggested PAD Layout





Symbol	Millimeters			
Symbol	Min	Nom	Max	
Α	0.450	0.500	0.550	
A1	0 0.020		0.050	
E1	0.013	0.063	0.113	
D	0.900	1.000	1.100	
Е	0.500	0.600	0.700	
е	0.65BSC			
L	0.150	0.250	0.350	
b	0.400	0.500	0.600	
L1	0.300	0.400	0.500	

Ordering Information

Device	Marking	Package	Quantity	Reel Size
ESD2.5V88D-C	N1	SOD-882/DFN1006	10,000pcs/Reel	7 inch